

## PATENT ABSTRACTS OF JAPAN

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### (54) EMBOSSED RELEASE MATERIAL AND PRODUCTION THEREOF

#### (57)Abstract:

PURPOSE: To obtain an embossing release material improved in the reproducibility of embossing, usable at high temp. and enhanced in the adhesiveness of a laminated layer and a support by laminating a polyolefin resin film subjected to embossing processing and the support not subjected to embossing processing by a radiation curable resin.

CONSTITUTION: An embossing release material is produced by subjecting a polyolefin resin film to embossing processing and applying a radiation curable resin to at least one of a support and the embossed polyolefin resin film to closely bond the embossed polyolefin resin film and the support through the radiation curable resin and curing the radiation curable resin by the irradiation with ultraviolet rays. Various additives such as pigment such as ultramarine or titanium oxide, a dye, an oxidation inhibitor, a fluorescent brightener or a stabilizer are added to the polyolefin resin film in an appropriate combination.